

2SJ410 Silicon P Channel MOS FET

REJ03G0863-0300 Rev.3.00 Jun 05, 2006

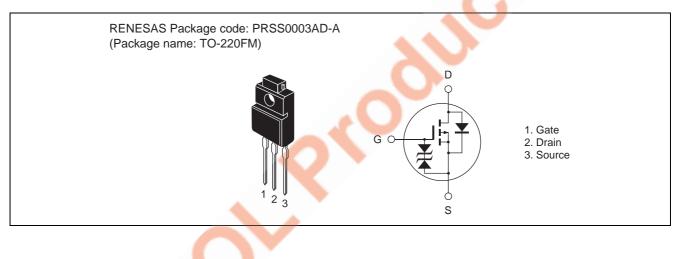
Description

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter and motor driver

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-200	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	-6	A
Drain peak current	I _{D (pulse)} Note 1	-24	A
Body to drain diode reverse drain current	I _{DR}	-6	A
Channel dissipation	Pch Note 2	30	W
Channel temperature	Tch	150	۵°
Storage temperature	Tstg	-55 to +150	۵°

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. Value at Tc = $25^{\circ}C$

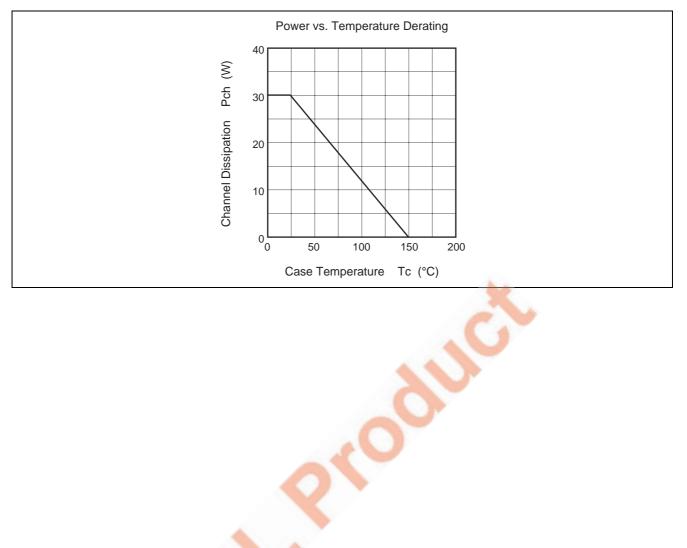
Electrical Characteristics

						(Ta = 25°C)
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-200	_	—	V	$I_{\rm D} = -10 \text{ mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20		—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	—		±10	μA	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	-	-250	μA	$V_{DS} = -160 \text{ V}, \text{ V}_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-2.0	—	-4.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	—	0.7	0.85	Ω	$I_D = -3 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	2.0	3.2		S	$I_D = -3 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss		900	_	pF	$V_{DS} = -10 V$
Output capacitance	Coss		280		pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		65		pF	f = 1 MHz
Turn-on delay time	t _{d (on)}		18	—	ns	$I_D = -3 A$
Rise time	tn	-	50	_	ns	$V_{GS} = -10 V$
Turn-off delay time	t _{d (off)}	—	90		ns	$R_L = 10 \Omega$
Fall time	tf		40		ns	
Body to drain diode forward voltage	V _{DF}	—	-1.0	—	V	$I_F = -6 A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	220	—	ns	$I_F = -6 A, V_{GS} = 0$
						di _F /dt = 50 A/µs

Note: 3. Pulse test



Main Characteristics

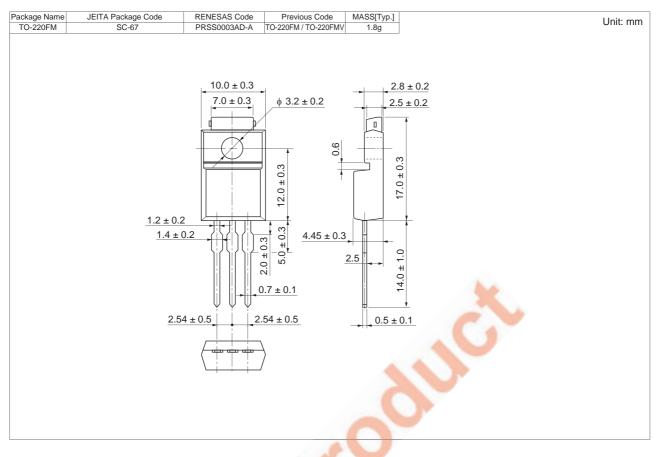


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Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ410-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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Renesas Technology Malaysia Sdn. Bhd Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510